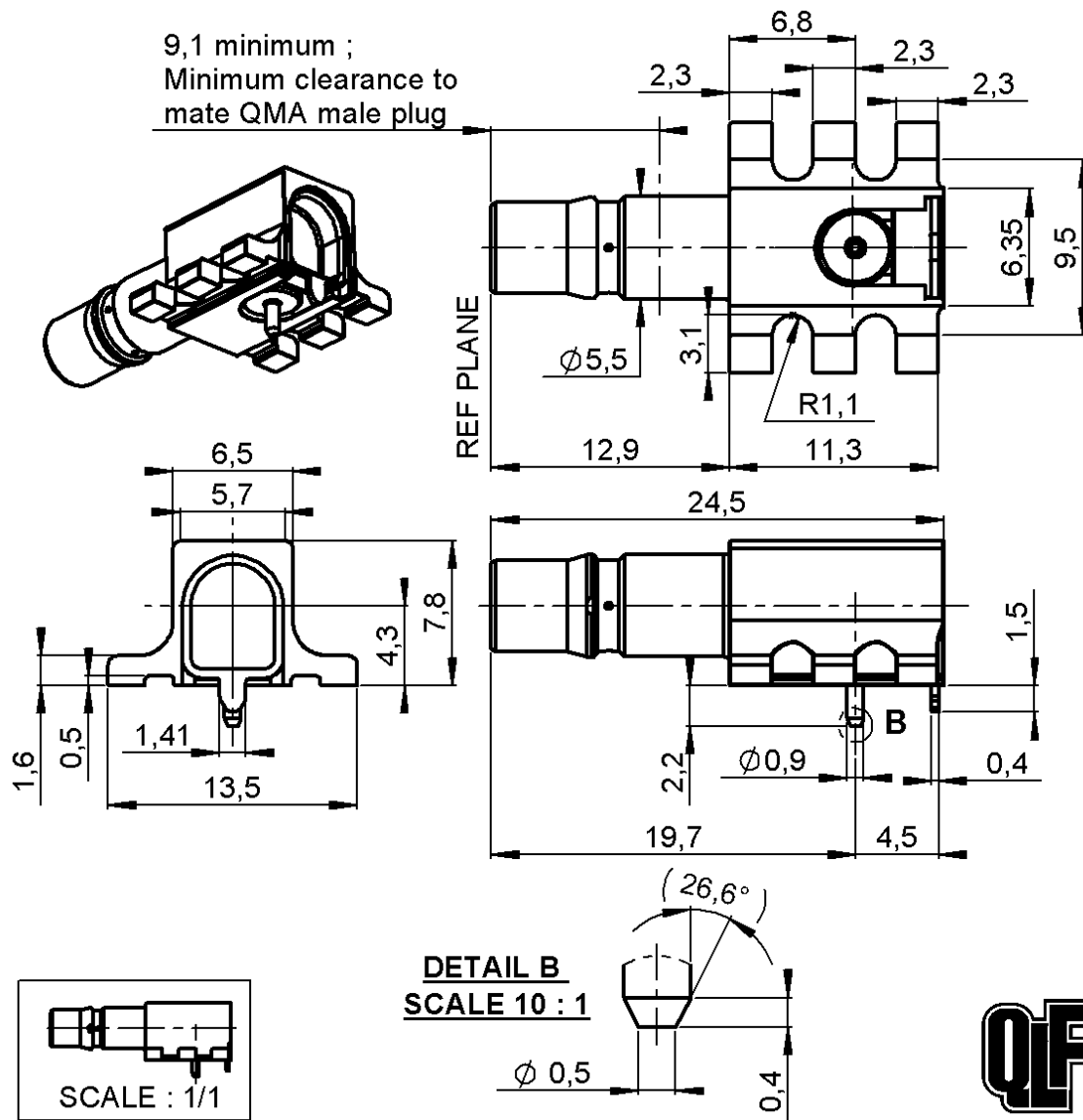


RIGHT ANGLE SMT RECEPTACLE

REEL PACKAGING PER 250

R123.682.867

Series : QMA


QF®


All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	DIE CAST ZINC ALLOY	GBR 2
CENTER CONTACT	BERYLLIUM COPPER	NPGR
OUTER CONTACT	-	-
INSULATOR	PTFE	-
GASKET	-	-
OTHERS PARTS	BRASS	GBR 2
-	-	-
-	-	-

Issue : 0722 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



RIGHT ANGLE SMT RECEPTACLE**R123.682.867****REEL PACKAGING PER 250****Series : QMA****PACKAGING**

Standard	Unit	Other
250	'W' option	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	0-6	GHz
VSWR	* + 0,0000	x F(GHz) Maxi
Insertion loss	0.05	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (**80	- F(GHz)) dB Maxi
Voltage rating	350	Veff Maxi
Dielectric withstanding voltage	1000	Veff mini
Insulation resistance	5000	M Ω mini

ENVIRONMENTAL

Operating temperature	-40/+105	$^{\circ}\text{C}$
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction

Others :

*VSWR Interf.only <1.05 maxi de 0 à 3Ghz

*VSWR Interf.only <1.10 maxi de 3 à 6Ghz

**RF leakage Interf.only 3<F<6Ghz: >70dB

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	27 N mini
Axial force – Opposite end	27 N mini
Torque	NA N.cm mini

Recommended torque

Mating	NA N.cm
Panel nut	NA N.cm

Mating life	100 Cycles mini
Weight	5,3290 g

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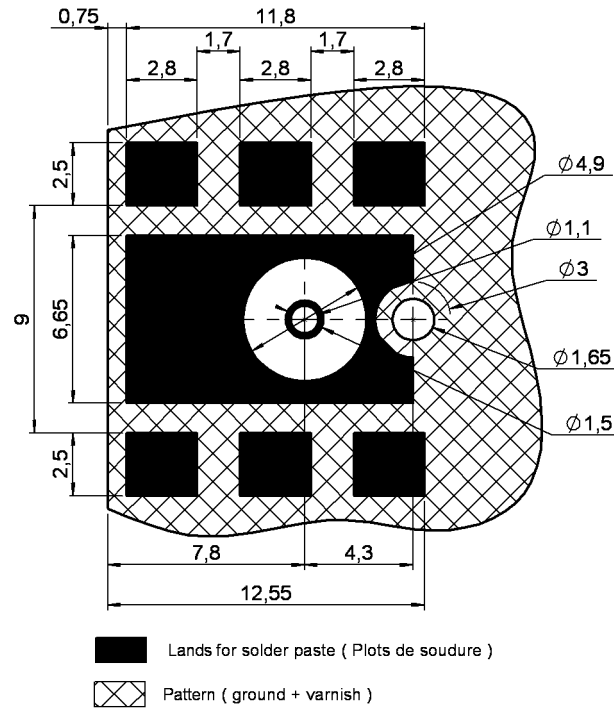
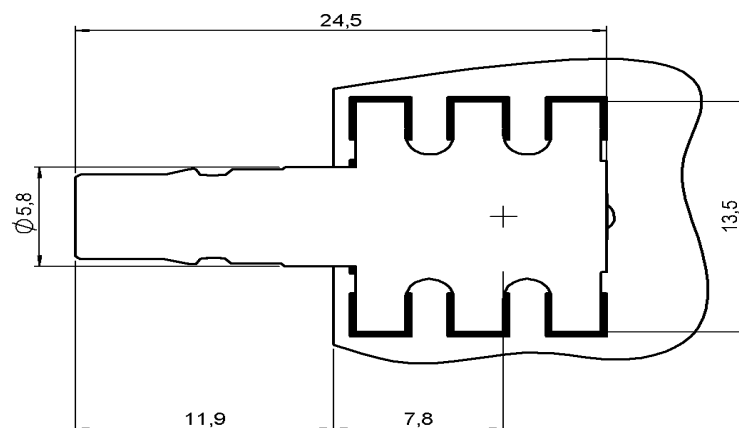
RIGHT ANGLE SMT RECEPTACLE**REEL PACKAGING PER 250****R123.682.867**

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QUICKLOCK SERIE – INFORMATIONS

COPLANAR LINE : Pattern and signal are on the same side. Thickness of PCB = 0.063 (1.6mm).

The material of PCB is the epoxy resin of glass fabrics bacs ($\epsilon_r = 4.8$). The solder resist should be printed except for the land pattern on the PCB.

**SHADOW OF QUICKLOCK RECEPTACLE FOR VIDEO CAMERA**

Issue : 0722 A

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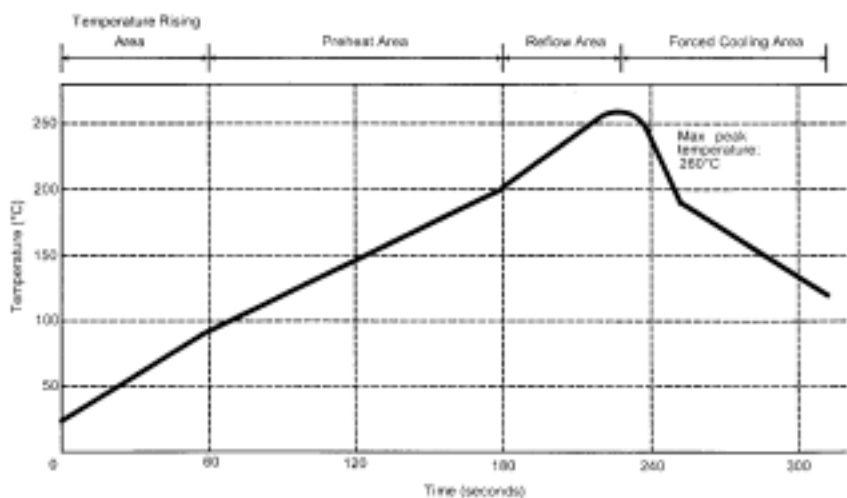


RIGHT ANGLE SMT RECEPTACLE**REEL PACKAGING PER 250****R123.682.867**

Series : QMA

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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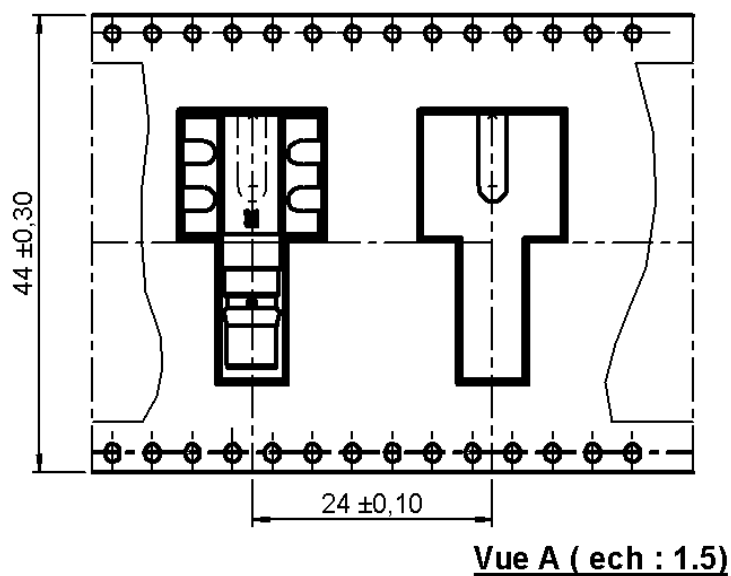
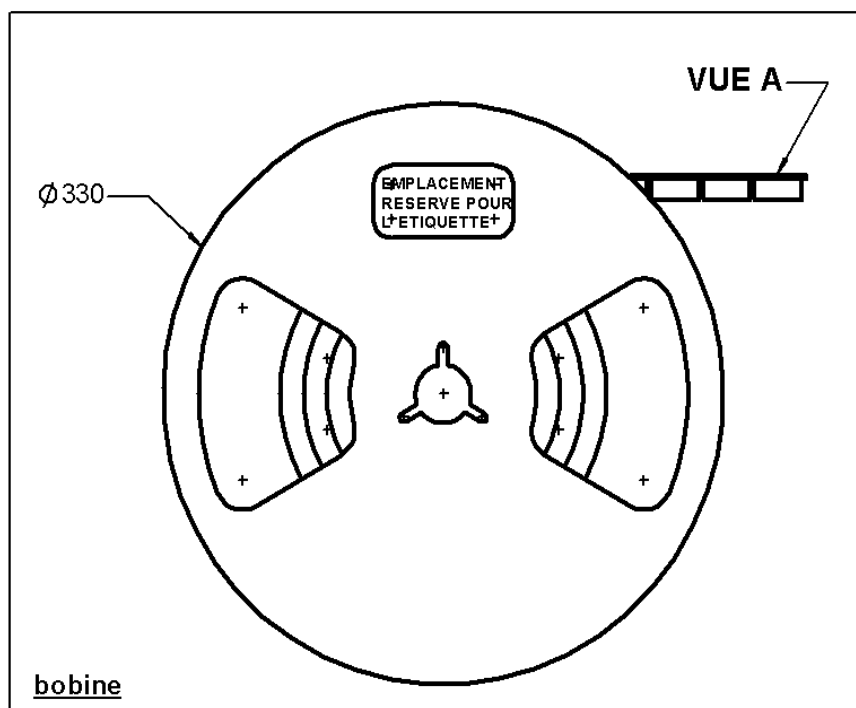


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